

# GTL2014

## 4-bit LVTTTL to GTL transceiver

Rev. 3.1 — 16 August 2021

Product data sheet

## 1 General description

The GTL2014 is a 4-bit translating transceiver designed for 3.3 V LVTTTL system interface with a GTL-/GTL/GTL+ bus, where GTL-/GTL/GTL+ refers to the reference voltage of the GTL bus and the input/output voltage thresholds associated with it.

The direction pin allows the part to function as either a GTL to LVTTTL sampling receiver or as a LVTTTL to GTL interface.

The GTL2014 LVTTTL inputs (only) are tolerant up to 5.5 V allowing direct access to TTL or 5 V CMOS inputs. The LVTTTL outputs are not 5.5 V tolerant.

The GTL2014 GTL inputs and outputs operate up to 3.6 V, allowing the device to be used in higher voltage open-drain output applications.

GTL2014 is pin-to-pin backward compatible to the GTL2005 (labels for A port and B port are interchanged). GTL2014's  $V_{ref}$  tracks down to 0.5 V for low voltage CPU, propagation delays are slightly longer, while GTL2005's  $V_{ref}$  linearity degrades below 0.8 V and has shorter propagation delay.

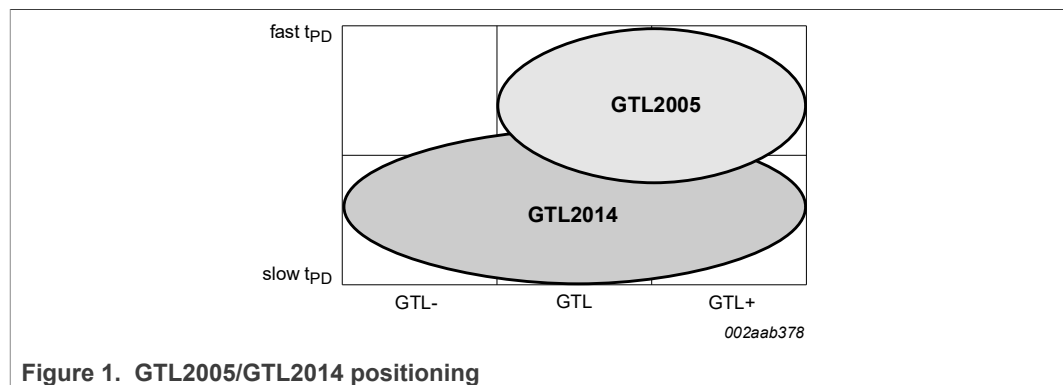


Figure 1. GTL2005/GTL2014 positioning

## 2 Features and benefits

- Operates as a 4-bit GTL-/GTL/GTL+ sampling receiver or as a LVTTTL to GTL-/GTL/GTL+ driver
- 3.0 V to 3.6 V operation with 5 V tolerant LVTTTL input
- GTL input and output 3.6 V tolerant
- $V_{ref}$  adjustable from 0.5 V to  $V_{CC}/2$
- Partial power-down permitted
- ESD protection exceeds 2000 V HBM per JESD22-A114 and 1000 V CDM per JESD22-CC101
- Latch-up protection exceeds 500 mA per JESD78
- Package offered: TSSOP14



### 3 Quick reference data

Table 1. Quick reference data

 $T_{amb} = 25\text{ }^{\circ}\text{C}$ 

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_{PLH}$	LOW to HIGH propagation delay	An-to-Bn; $C_L = 50\text{ pF}$ ; $V_{CC} = 3.3\text{ V}$	-	2.8	-	ns
$t_{PHL}$	HIGH to LOW propagation delay	An-to-Bn; $C_L = 50\text{ pF}$ ; $V_{CC} = 3.3\text{ V}$	-	3.4	-	ns
$t_{PLH}$	LOW to HIGH propagation delay	Bn-to-An; $C_L = 50\text{ pF}$ ; $V_{CC} = 3.3\text{ V}$	-	5.2	-	ns
$t_{PHL}$	HIGH to LOW propagation delay	Bn-to-An; $C_L = 50\text{ pF}$ ; $V_{CC} = 3.3\text{ V}$	-	4.9	-	ns
$C_i$	input capacitance	control inputs; $V_I = 3.0\text{ V}$ or $0\text{ V}$	-	2	2.5	pF
$C_{io}$	input/output capacitance	A port; $V_O = 3.0\text{ V}$ or $0\text{ V}$	-	4.6	6	pF
		B port; $V_O = V_{TT}$ or $0\text{ V}$	-	3.4	4.3	pF

### 4 Ordering information

Table 2. Ordering information

Type number	Topside mark	Package		Version
		Name	Description	
GTL2014PW	GTL2014	TSSOP14	plastic thin shrink small outline package; 10 leads; body width 4.4 mm	SOT402-1

Standard packing quantities and other packaging data are available at [www.nxp.com/packages/](http://www.nxp.com/packages/).

#### 4.1 Ordering options

Table 3. Ordering options

Type number	Orderable part number	Package	Packing method	Minimum order quantity	Temperature
GTL2014PW	GTL2014PW, 118 <sup>[1]</sup>	TSSOP14	REEL 13" Q1/T1 *STANDARD MARK	2500	$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$
GTL2014PW	GTL2014PWZ	TSSOP14	REEL 13" Q1/T1 *STANDARD MARK SSB <sup>[2]</sup>	2500	$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$

[1] Discontinued in 202108008DN - drop in replacement is GTL2014PWZ - this is documented in PCN:202102035F01.

[2] This packing method uses a Static Shielding Bag (SSB) solution. Material should be kept in the sealed bag between uses.

## 5 Functional diagram

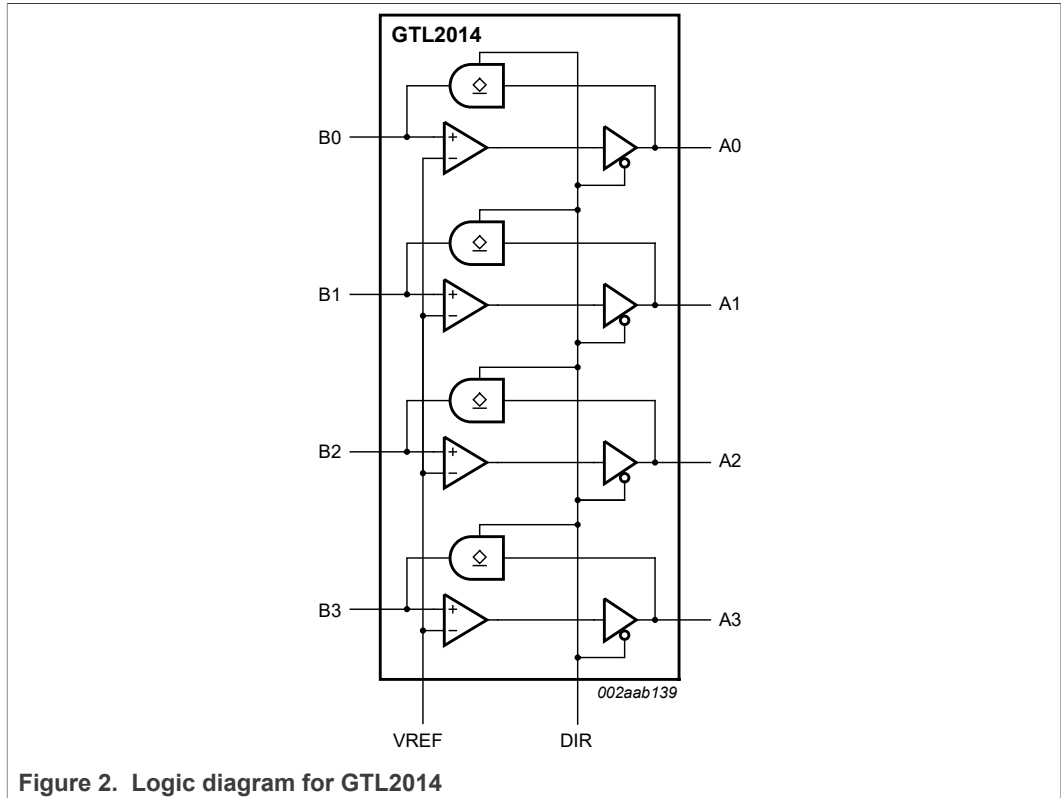


Figure 2. Logic diagram for GTL2014

## 6 Pinning information

### 6.1 Pinning

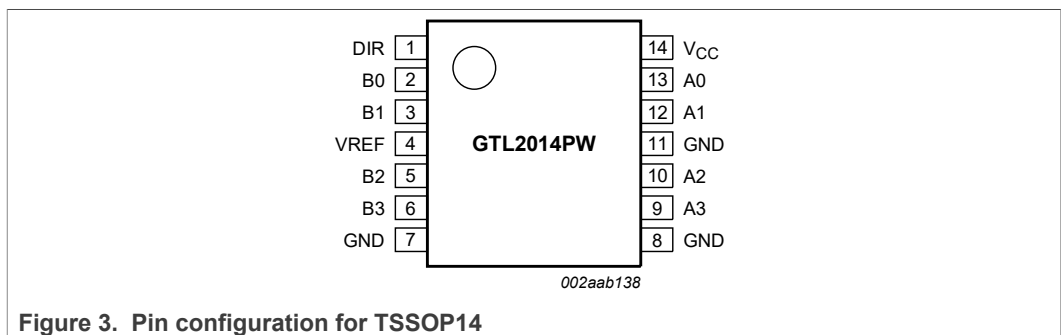


Figure 3. Pin configuration for TSSOP14

### 6.2 Pin description

Table 4. Pin description

Symbol	Pin	Description
DIR	1	direction control input (LVTTTL)
B0	2	data inputs/outputs (GTL)

Table 4. Pin description...continued

Symbol	Pin	Description
B1	3	
B2	5	
B3	6	
A0	13	data inputs/outputs (LVTTTL)
A1	12	
A2	10	
A3	9	
VREF	4	GTL reference voltage
GND	7, 8, 11	ground (0 V)
V <sub>CC</sub>	14	positive supply voltage

## 7 Functional description

Refer to [Figure 2](#).

### 7.1 Function table

Table 5. Function table

H = HIGH voltage level; L = LOW voltage level.

Input	Input/output	
DIR	A (LVTTTL)	B (GTL)
H	input	B <sub>n</sub> = A <sub>n</sub>
L	A <sub>n</sub> = B <sub>n</sub>	input

## 8 Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).<sup>[1]</sup>

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+4.6	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0 V	-	-50	mA
V <sub>I</sub>	input voltage	A port	-0.5 <sup>[2]</sup>	+7.0	V
		B port	-0.5 <sup>[2]</sup>	+4.6	V
I <sub>OK</sub>	output clamping current	A port; V <sub>O</sub> < 0 V	-	-50	mA
V <sub>O</sub>	output voltage	output in OFF or HIGH state			
		A port	-0.5 <sup>[2]</sup>	+7.0	V
		B port	-0.5 <sup>[2]</sup>	+4.6	V
I <sub>OL</sub>	LOW-level output current	current into any output in the LOW state			

Table 6. Limiting values...continued

In accordance with the Absolute Maximum Rating System (IEC 60134).<sup>[1]</sup>

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
		A port	-	32	mA
		B port	-	80	mA
$I_{OH}$	HIGH-level output current	current into any output in the HIGH state; A port	-	-32	mA
$T_{stg}$	storage temperature		<sup>[3]</sup> -60	+150	°C

[1] Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under [Section 9](#) is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[2] The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

[3] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

## 9 Recommended operating conditions

Table 7. Operating conditions <sup>[1]</sup>

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		3.0	-	3.6	V
$V_{TT}$	termination voltage <sup>[2]</sup>	GTL-	0.85	0.9	0.95	V
		GTL	1.14	1.2	1.26	V
		GTL+	1.35	1.5	1.65	V
$V_{ref}$	reference voltage	overall	0.5	$\frac{2}{3}V_{TT}$	$V_{CC}/2$	V
		GTL-	0.5	0.6	0.63	V
		GTL	0.76	0.8	0.84	V
		GTL+	0.87	1.0	1.10	V
$V_I$	input voltage	B port	0	$V_{TT}$	3.6	V
		except B port	0	3.3	5.5 <sup>[3]</sup>	V
$V_{IH}$	HIGH-level input voltage	B port	$V_{ref} + 0.050$	-	-	V
		except B port	2	-	-	V
$V_{IL}$	LOW-level input voltage	B port	-	-	$V_{ref} - 0.050$	V
		except B port	-	-	0.8	V
$I_{OH}$	HIGH-level output current	A port	-	-	-16	mA
$I_{OL}$	LOW-level output current	B port	-	-	40	mA
		A port	-	-	16	mA
$T_{amb}$	ambient temperature	operating in free-air	-40	-	+85	°C

[1] Unused inputs must be held HIGH or LOW to prevent them from floating.

[2]  $V_{TT}$  maximum of 3.6 V with resistor sized so  $I_{OL}$  maximum is not exceeded.

[3] A0, A1, A2, A3  $V_{I(max)}$  is 3.6 V if configured as outputs (DIR = L).

## 10 Static characteristics

**Table 8. Static characteristics**

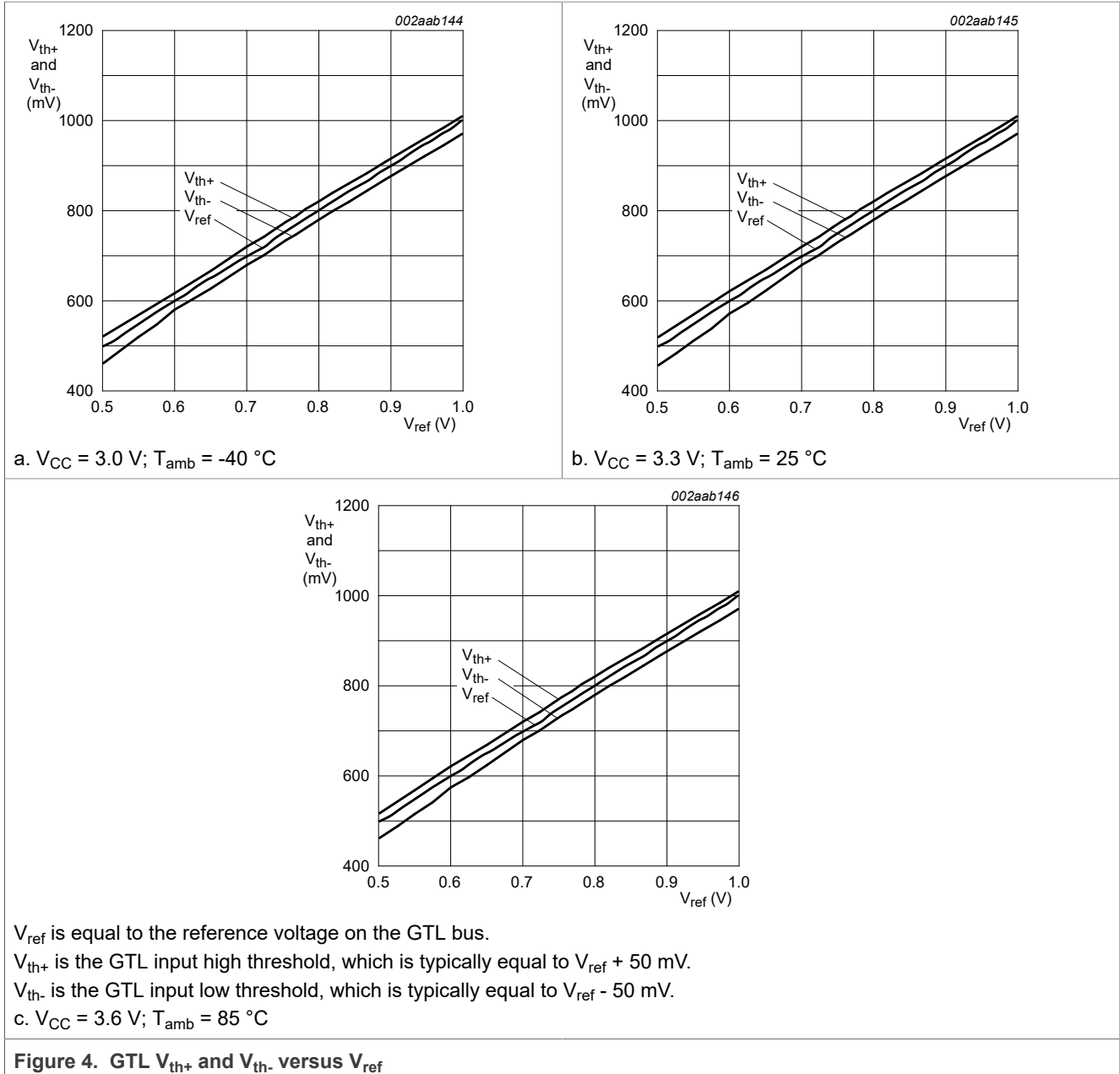
Recommended operating conditions; voltages are referenced to GND (ground = 0 V).  $T_{amb} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$

Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
V <sub>OH</sub>	HIGH-level output voltage	A port; V <sub>CC</sub> = 3.0 V to 3.6 V; I <sub>OH</sub> = -100 μA <sup>[2]</sup>	V <sub>CC</sub> - 0.2	-	-	V
		A port; V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -16 mA <sup>[2]</sup>	2.0	-	-	V
V <sub>OL</sub>	LOW-level output voltage	B port; V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 40 mA <sup>[2]</sup>	-	0.23	0.4	V
		A port; V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 8 mA <sup>[2]</sup>	-	0.28	0.4	V
		A port; V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 12 mA <sup>[2]</sup>	-	0.40	0.55	V
		A port; V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 16 mA <sup>[2]</sup>	-	0.55	0.8	V
I <sub>I</sub>	input current	control inputs; V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>CC</sub> or GND	-	-	±1	μA
		B port; V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>TT</sub> or GND	-	-	±1	μA
		A port; V <sub>CC</sub> = 0 V or 3.6 V; V <sub>I</sub> = 5.5 V	-	-	10	μA
		A port; V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>CC</sub>	-	-	±1	μA
		A port; V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = 0 V	-	-	-5	μA
I <sub>OZ</sub>	OFF-state output current	A port; V <sub>CC</sub> = 0 V; V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V	-	-	±100	μA
I <sub>CC</sub>	quiescent supply current	A port; V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 mA	-	4	10	mA
		B port; V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>TT</sub> or GND; I <sub>O</sub> = 0 mA	-	4	10	mA
ΔI <sub>CC</sub> <sup>[3]</sup>	additional quiescent current (per input)	A port or control inputs; V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V	-	-	500	μA
C <sub>i</sub>	input capacitance	control inputs; V <sub>I</sub> = 3.0 V or 0 V	-	2	2.5	pF
C <sub>io</sub>	input/output capacitance	A port; V <sub>O</sub> = 3.0 V or 0 V	-	4.6	6	pF
		B port; V <sub>O</sub> = V <sub>TT</sub> or 0 V	-	3.4	4.3	pF

[1] All typical values are measured at V<sub>CC</sub> = 3.3 V and T<sub>amb</sub> = 25 °C.

[2] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[3] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.



## 11 Dynamic characteristics

**Table 9. Dynamic characteristics**

$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$

Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
<b>GTL-</b> ; $V_{ref} = 0.6\text{ V}; V_{TT} = 0.9\text{ V}$						
$t_{PLH}$	LOW to HIGH propagation delay	An to Bn; see <a href="#">Figure 5</a>	-	2.8	5	ns
$t_{PHL}$	HIGH to LOW propagation delay	An to Bn; see <a href="#">Figure 5</a>	-	3.3	7	ns
$t_{PLH}$	LOW to HIGH propagation delay	Bn to An; see <a href="#">Figure 6</a>	-	5.3	8	ns

Table 9. Dynamic characteristics...continued

$V_{CC} = 3.3 V \pm 0.3 V$

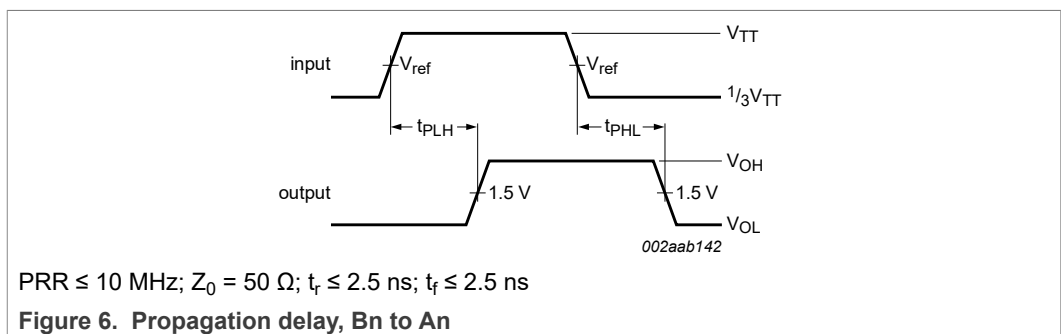
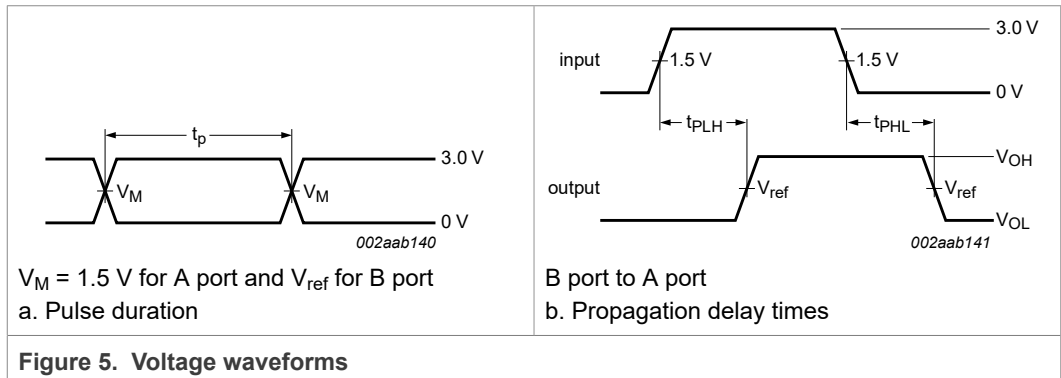
Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
$t_{PHL}$	HIGH to LOW propagation delay	Bn to An; see <a href="#">Figure 6</a>	-	5.2	8	ns
<b>GTL; <math>V_{ref} = 0.8 V</math>; <math>V_{TT} = 1.2 V</math></b>						
$t_{PLH}$	LOW to HIGH propagation delay	An to Bn; see <a href="#">Figure 5</a>	-	2.8	5	ns
$t_{PHL}$	HIGH to LOW propagation delay	An to Bn; see <a href="#">Figure 5</a>	-	3.4	7	ns
$t_{PLH}$	LOW to HIGH propagation delay	Bn to An; see <a href="#">Figure 6</a>	-	5.2	8	ns
$t_{PHL}$	HIGH to LOW propagation delay	Bn to An; see <a href="#">Figure 6</a>	-	4.9	7	ns
<b>GTL+; <math>V_{ref} = 1.0 V</math>; <math>V_{TT} = 1.5 V</math></b>						
$t_{PLH}$	LOW to HIGH propagation delay	An to Bn; see <a href="#">Figure 5</a>	-	2.8	5	ns
$t_{PHL}$	HIGH to LOW propagation delay	An to Bn; see <a href="#">Figure 5</a>	-	3.4	7	ns
$t_{PLH}$	LOW to HIGH propagation delay	Bn to An; see <a href="#">Figure 6</a>	-	5.1	8	ns
$t_{PHL}$	HIGH to LOW propagation delay	Bn to An; see <a href="#">Figure 6</a>	-	4.7	7	ns

[1] All typical values are measured at  $V_{CC} = 3.3 V$  and  $T_{amb} = 25 ^\circ C$ .

1. All typical values are at  $V_{CC} = 3.3 V$  and  $T_{amb} = 25 ^\circ C$ .

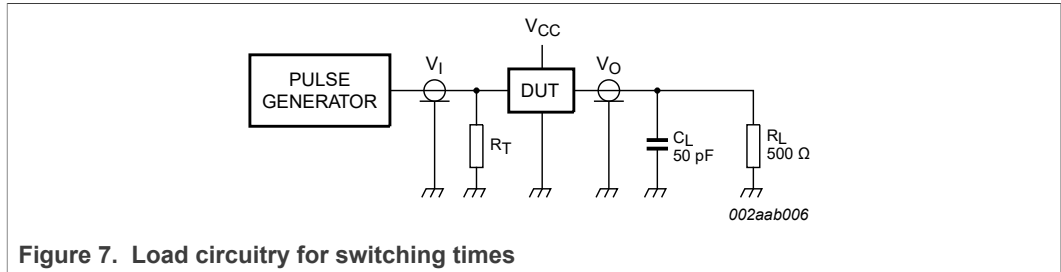
11.1 Waveforms

$V_M = 1.5 V$  at  $V_{CC} \geq 3.0 V$ ;  $V_M = V_{CC}/2$  at  $V_{CC} \leq 2.7 V$  for A ports and control pins;  $V_M = V_{ref}$  for B ports.

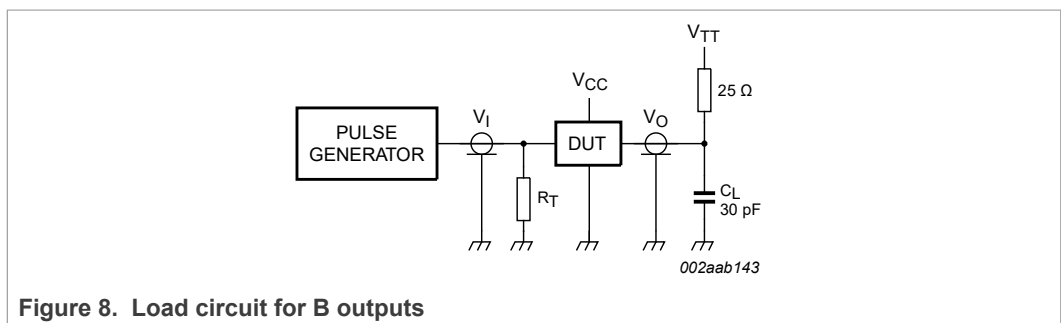




**12 Test information**



**Figure 7. Load circuitry for switching times**



**Figure 8. Load circuit for B outputs**

**R<sub>L</sub>**

Load resistor

**C<sub>L</sub>**

Load capacitance; includes jig and probe capacitance

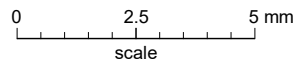
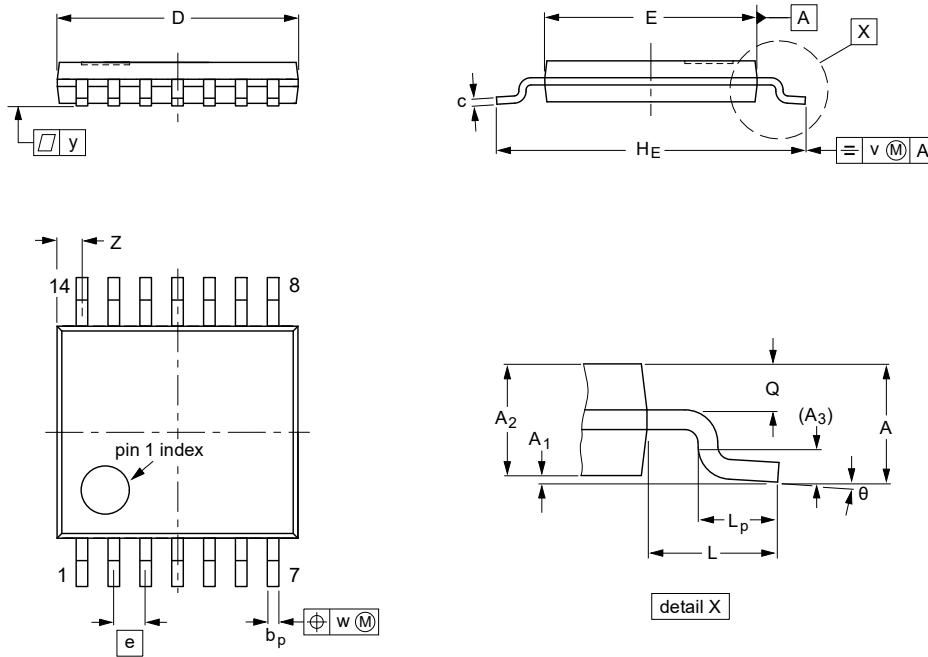
**R<sub>T</sub>**

Termination resistance; should be equal to output impedance of pulse generators.

13 Package outline

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT402-1		MO-153				99-12-27 03-02-18

Figure 9. Package outline SOT402-1 (TSSOP14)

## 14 Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note AN10365 “Surface mount reflow soldering description”.

### 14.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

### 14.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

### 14.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

### 14.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see [Figure 10](#)) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with [Table 10](#) and [Table 11](#)

**Table 10. SnPb eutectic process (from J-STD-020D)**

Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm <sup>3</sup> )	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

**Table 11. Lead-free process (from J-STD-020D)**

Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm <sup>3</sup> )		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see [Figure 10](#).

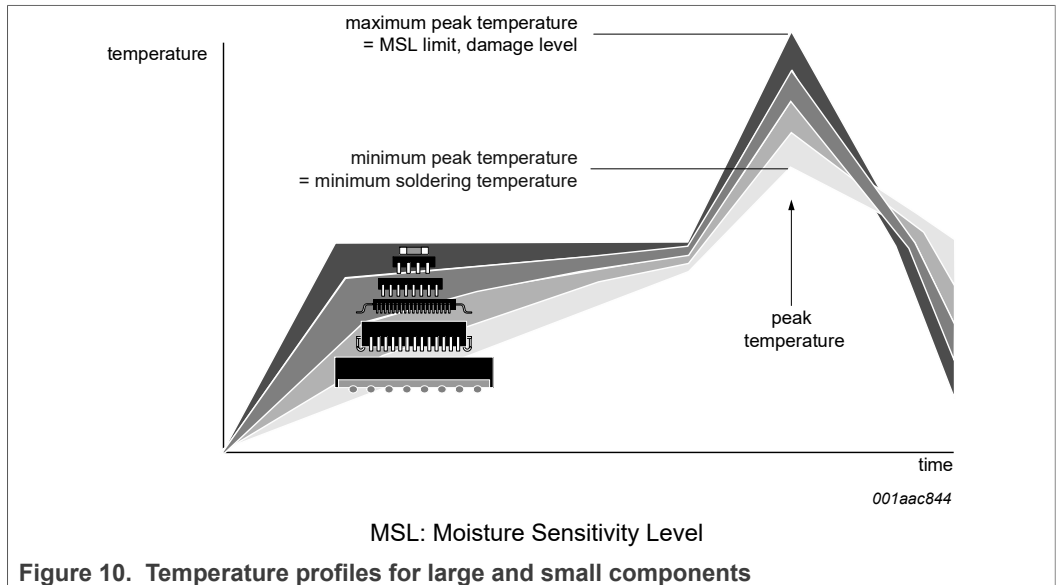


Figure 10. Temperature profiles for large and small components

For further information on temperature profiles, refer to Application Note AN10365 “Surface mount reflow soldering description”.

## 15 Abbreviations

Table 12. Abbreviations

Acronym	Description
CDM	Charged-Device Model
CMOS	Complementary Metal-Oxide Semiconductor
CPU	Central Processing Unit
ESD	ElectroStatic Discharge
GTL	Gunning Transceiver Logic
HBM	Human Body Model
LVTTTL	Low Voltage Transistor-Transistor Logic
PRR	Pulse Rate Repetition
TTL	Transistor-Transistor Logic

## 16 Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
GTL2014 v.3.1	20210816	Product data sheet	PCN:202102035F01	GTL2014 v.3
GTL2014 v.3	20120614	Product data sheet	-	GTL2014 v.2
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Section 1</a>, first paragraph, first sentence: added phrase "where GTL-/GTL/GTL+ refers to the reference voltage of the GTL bus and the input/output voltage thresholds associated with it"</li> <li>• Added (new) <a href="#">Figure 4</a></li> </ul>			
GTL2014 v.2	20120306	Product data sheet	-	GTL2014 v.1

Table 13. Revision history...continued

Document ID	Release date	Data sheet status	Change notice	Supersedes
GTL2014 v.1 (9397 750 13534)	20050519	Product data sheet	-	-

## 17 Legal information

### 17.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

### 17.2 Definitions

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